Silicon Controlled Rectifiers

Reverse Blocking Thyristors

Designed primarily for half-wave ac control applications, such as motor controls, heating controls, and power supplies; or wherever half-wave silicon gate-controlled devices are needed.

Features

- Blocking Voltage to 800 Volts
- On-State Current Rating of 12 Amperes RMS at 80°C
- High Surge Current Capability 100 Amperes
- Rugged, Economical TO-220AB Package
- Glass Passivated Junctions for Reliability and Uniformity
- Minimum and Maximum Values of IGT, VGT an IH Specified for Ease of Design
- High Immunity to dv/dt 100 V/µsec Minimum at 125°C
- These are Pb-Free Devices

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

Rating	Symbol	Value	Unit
Peak Repetitive Off–State Voltage (Note 1) (T _J = -40 to 125°C, Sine Wave, 50 to 60 Hz, Gate Open)	$V_{ m DRM,} \ V_{ m RRM}$		V
MCR12D MCR12M MCR12N		400 600 800	
On-State RMS Current (180° Conduction Angles; T _C = 80°C)	I _{T(RMS)}	12	Α
Peak Non-repetitive Surge Current (1/2 Cycle, Sine Wave 60 Hz, T _J = 125°C)	I _{TSM}	100	Α
Circuit Fusing Consideration (t = 8.33 ms)	I ² t	41	A ² sec
Forward Peak Gate Power (Pulse Width ≤ 1.0 μs, T _C = 80°C)	P _{GM}	5.0	W
Forward Average Gate Power (t = 8.3 ms, T _C = 80°C)	P _{G(AV)}	0.5	W
Average On-State Current (180° Conduction Angles; T _C = 80°C)	I _{T(AV)}	7.8	Α
Forward Peak Gate Current (Pulse Width ≤ 1.0 μs, T _C = 90°C)	I _{GM}	2.0	Α
Operating Junction Temperature Range	T_{J}	-40 to +125	°C
Storage Temperature Range	T _{stg}	-40 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

 V_{DRM} and V_{RRM} for all types can be applied on a continuous basis. Ratings apply for zero or negative gate voltage; positive gate voltage shall not be applied concurrent with negative potential on the anode. Blocking voltages shall not be tested with a constant current source such that the voltage ratings of the devices are exceeded.



ON Semiconductor®

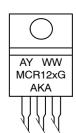
http://onsemi.com

SCRs 12 AMPERES RMS 400 thru 800 VOLTS



MARKING DIAGRAM





TO-220 CASE 221A-09 STYLE 3

= Assembly Location

Y = Year

WW = Work Week x = D, M, or N

G = Pb-Free Package

AKA = Diode Polarity

PIN ASSIGNMENT		
1	Cathode	
2	Anode	
3	Gate	
4	Anode	

ORDERING INFORMATION

Device	Package	Shipping
MCR12DG	TO-220AB (Pb-Free)	50 Units / Rail
MCR12MG	TO-220AB (Pb-Free)	50 Units / Rail
MCR12NG	TO-220AB (Pb-Free)	50 Units / Rail

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case Junction-to-Ambient	$R_{ hetaJC} \ R_{ hetaJA}$	2.2 62.5	°C/W
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	T _L	260	°C

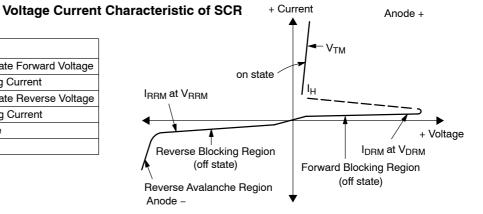
Characteristic	Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS					
$\label{eq:peak_repetitive} $	I _{DRM} , I _{RRM}	_ _	_ _	0.01 2.0	mA
ON CHARACTERISTICS					
Peak Forward On-State Voltage (Note 2) (I _{TM} = 24 A)	V _{TM}	-	-	2.2	V
Gate Trigger Current (Continuous dc) (V_D = 12 V; R_L = 100 Ω)	I _{GT}	2.0	8.0	20	mA
Holding Current (V _D = 12 V, Gate Open, Initiating Current = 200 mA)	I _H	4.0	20	40	mA
Latch Current (V _D = 12 V, I _G = 20 mA)	IL	6.0	25	60	mA
Gate Trigger Voltage (Continuous dc) ($V_D = 12 \text{ V}; R_L = 100 \Omega$)	V _{GT}	0.5	0.65	1.0	V
DYNAMIC CHARACTERISTICS					
Critical Rate of Rise of Off-State Voltage	dv/dt	100	250	_	V/μs

IPK = 50 A, Pw = 40 μsec, diG/dt = 1 A/μsec, lgt = 50 mA 2. Indicates Pulse Test: Pulse Width \leq 2.0 ms, Duty Cycle \leq 2%.

Repetitive Critical Rate of Rise of On-State Current

(V_D = Rated V_{DRM}, Exponential Waveform, Gate Open, T_J = 125°C)

Symbol Parameter VDRM Peak Repetitive Off State Forward Voltage IDRM Peak Forward Blocking Current VRRM Peak Repetitive Off State Reverse Voltage IRRM Peak Reverse Blocking Current VTM Peak On State Voltage IH Holding Current



di/dt

A/μs

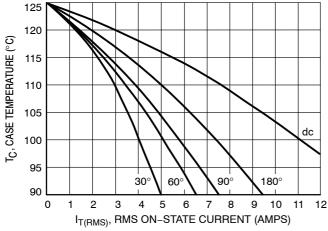


Figure 1. Typical RMS Current Derating

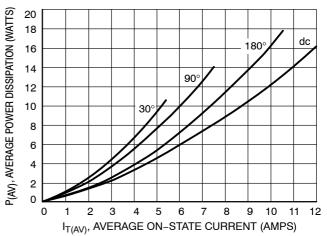


Figure 2. On-State Power Dissipation

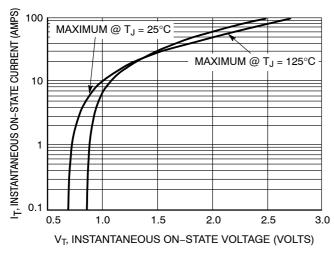


Figure 3. Typical On-State Characteristics

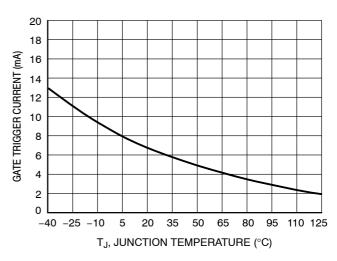


Figure 4. Typical Gate Trigger Current versus Junction Temperature

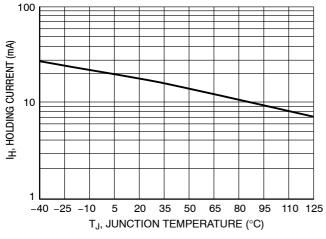


Figure 5. Typical Holding Current versus Junction Temperature

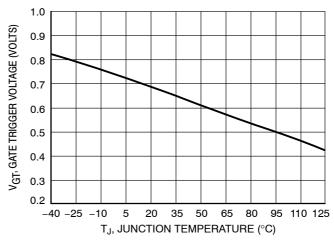


Figure 6. Typical Gate Trigger Voltage versus
Junction Temperature

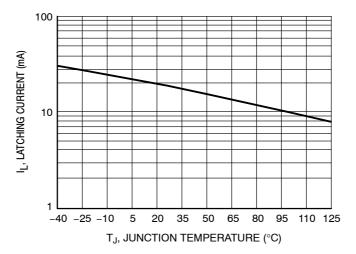
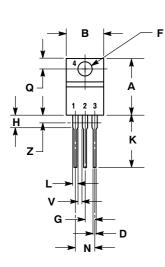
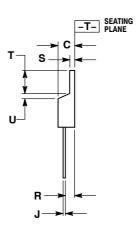


Figure 7. Typical Latching Current versus Junction Temperature

PACKAGE DIMENSIONS

TO-220 CASE 221A-09 ISSUE AG





NOTES

- DIMENSIONING AND TOLERANCING PER ANSI
 MARKATANA 1000
- Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH.
- 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.570	0.620	14.48	15.75
В	0.380	0.405	9.66	10.28
С	0.160	0.190	4.07	4.82
D	0.025	0.036	0.64	0.91
F	0.142	0.161	3.61	4.09
G	0.095	0.105	2.42	2.66
Н	0.110	0.161	2.80	4.10
J	0.014	0.025	0.36	0.64
K	0.500	0.562	12.70	14.27
L	0.045	0.060	1.15	1.52
N	0.190	0.210	4.83	5.33
Q	0.100	0.120	2.54	3.04
R	0.080	0.110	2.04	2.79
S	0.045	0.055	1.15	1.39
Т	0.235	0.255	5.97	6.47
U	0.000	0.050	0.00	1.27
٧	0.045		1.15	
Z		0.080		2.04

STYLE 3:

PIN 1. CATHODE

. ANODE

3 GATE

4. ANODE

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